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September 2006

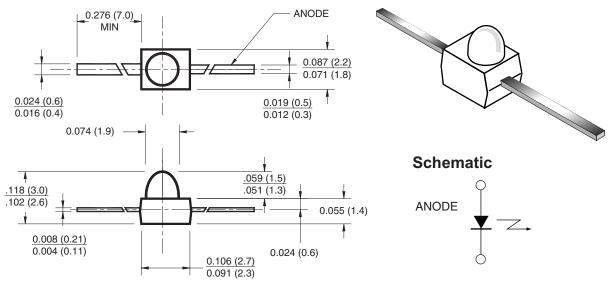
QEB363

Subminiature Plastic Infrared Emitting Diode

Features

- T-3/4 (2mm) Surface Mount Package
- Tape & Reel Option (See Tape & Reel Specifications)
- Lead Form Options: Gullwing, Yoke, Z-Bend
- Narrow Emission Angle, 24°
- Wavelength = 940nm, GaAs
- Clear Water Lens
- Matched Photosensor: QSB363
- High Radiant Intensity

Package Dimensions



Notes:

- 1. Dimensions are in inches (mm).
- 2. Tolerance of ±.010 (.25) on all non nominal dimensions unless otherwise specified.

Absolute Maximum Ratings (T_A = 25°C unless otherwise specified)

Symbol	Parameter	Rating	Unit
T _{OPR}	Operating Temperature	-40 to +100	°C
T _{STG}	Storage Temperature	-40 to +100	°C
T _{SOL-I}	Soldering Temperature (Iron) ^(2,3,4)	240 for 5 sec	°C
T _{SOL-F}	Soldering Temperature (Flow) ^(2,3)	260 for 10 sec	°C
I _F	Continuous Forward Current	50	mA
V _R	Reverse Voltage	5	V
P _D	Power Dissipation ⁽¹⁾	100	mW

Notes:

- 1. Derate power dissipation linearly 1.33mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron 1/16" (1.6mm) minimum from housing.

Electrical/Optical Characteristics (T_A = 25°C)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
λ_{P}	Peak Emission Wavelength	I _F = 100mA		940		nm
Θ	Emission Angle	I _F = 100mA		±12		0
V _F	Forward Voltage	I _F = 100mA, t _p = 20ms			1.6	V
I _R	Reverse Current	V _R = 5V			100	μΑ
I _e	Radiant Intensity	I _F = 100mA, tp = 20ms	8			mW/sr
t _r	Rise Time	I _F = 100mA		1		μs
t _f	Fall Time	t _p = 20ms		1		μs

Typical Performance Curves

Fig. 1 Maximum Forward Current vs. Temperature

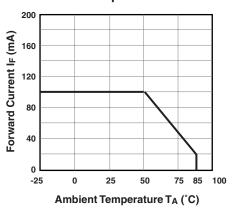


Fig. 3 Peak Emission Wavelength vs. Ambient Temperature

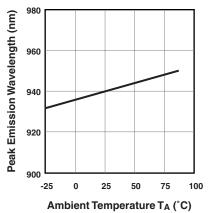


Fig. 5 Relative Radiant Flux vs. Ambient Temperature

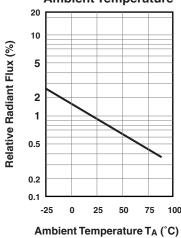


Fig. 2 Relative Radiant Intensity vs. Wavelength

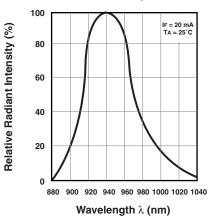


Fig. 4 Forward Current vs. Forward Voltage

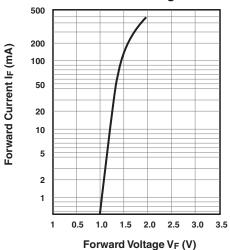
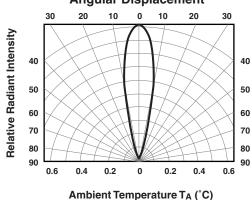


Fig. 6 Relative Radiant Intensity vs.
Angular Displacement

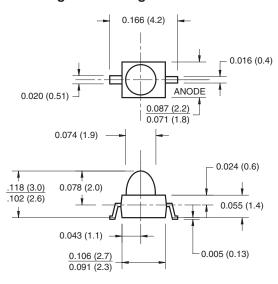


Surface Mount Options for T-3/4 Package

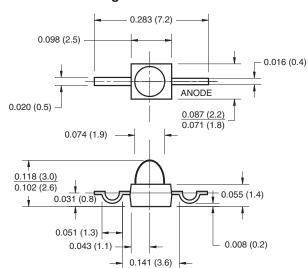
Features

- Three lead forming options: Gull Wing, Yoke and Z-Bend
- Compatible with automatic placement equipment
- Supplied on tape and reel or in bulk packaging
- Compatible with vapor phase reflow solder processes

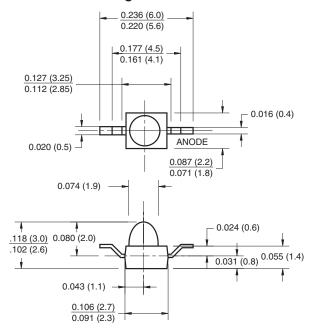
Gull Wing Lead Configuration



Yoke Lead Configuration



Z-Bend Lead Configuration



Notes: (Applies to all package drawings)

- 1. Dimensions are in inches (mm).
- 2. Tolerance of ±.010 (.25) on all non nominal dimensions unless otherwise specified.

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